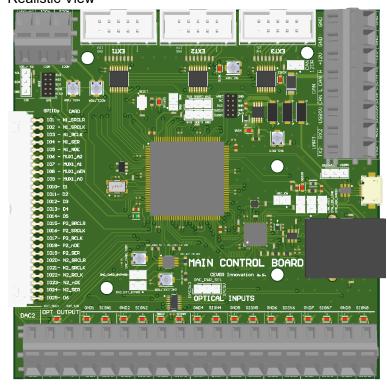
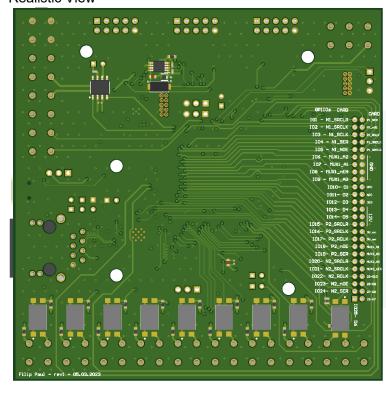
MAIN CONTROL BOARD

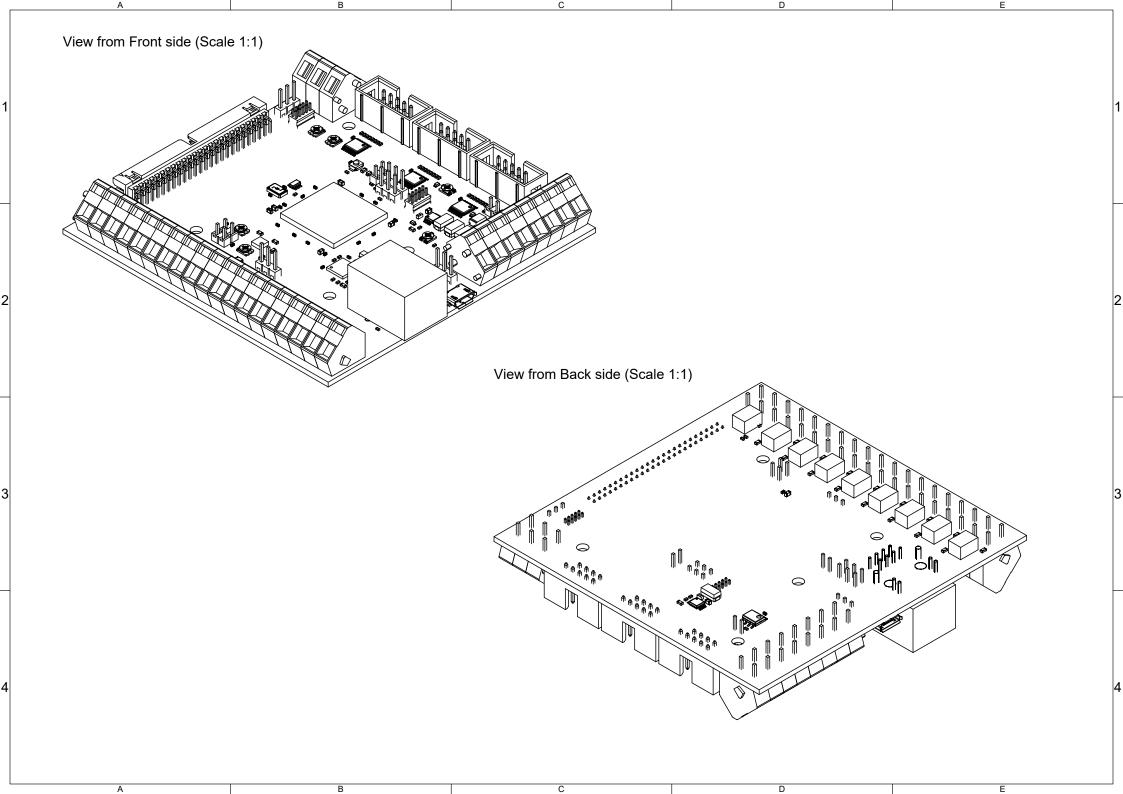
Realistic View



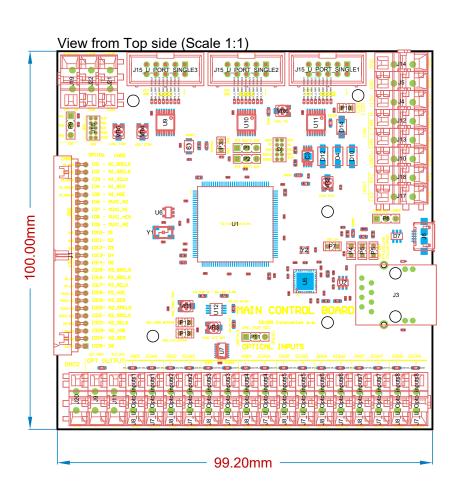
Realistic View

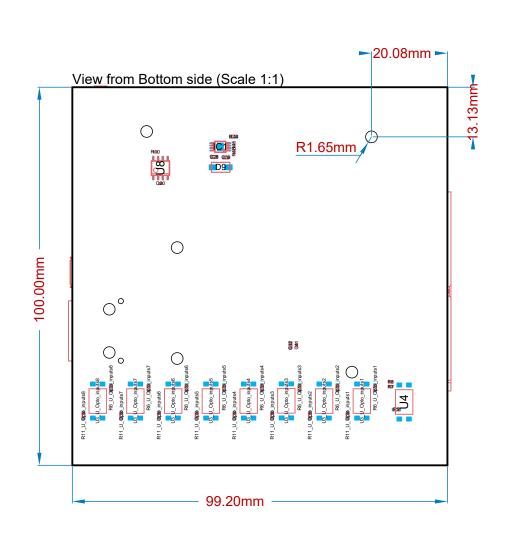


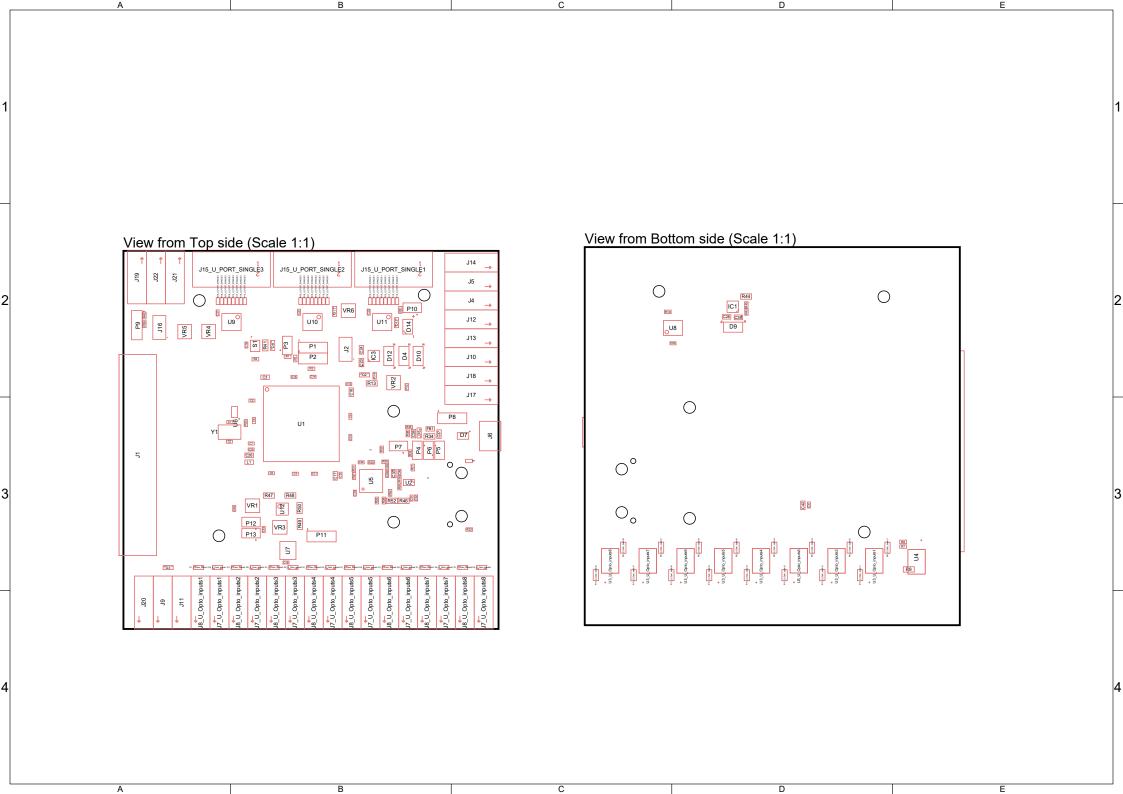
B C D



ASSEMBLY DRAWING







Impedance control stackup: **FABRICATION DRAWING USB** (top layer): USB_D_P and USB_D_N -> 90 Ohms diff, 50 GND Layer Stack Legend Thickness Dielectric Material Type Gerber Material Layer Top Overlay Legend GTO **ETHERNET** (top layer: Surface Material Top Solder Solder Resist Solder Mask GTS 0.02mm TD_P and TD_N -> 1000hms diff, 50 GND JLC_6_TOP **Top Layer** 0.04mm Signal **GTL** Prepreg 0.10mm JLC3313 Dielectric TD_P and RD_N -> 1000hms diff, 50GND JLC_6_INNER Inner Layer 2(GND) 0.02mm G1 Signal Bottom Layer 1 (Scale 1:1) Top Layer (Scale 1:1) .00000...00000...00000. Prepreg 0.55mm **JLCcore** Dielectric 0.02mm G2 Copper **Inner Layer 3** Signal LC2116 0.11mm Dielectric G3 0.02mm Copper **Inner Layer 4** Signal Prepreg 0.55mm **JLCcore** Dielectric JLC_6_INNER G4 Inner Layer 5 0.02mm Signal Prepreg 0.10mm JLC3313 Dielectric JLC_6_TOP **GBL Bottom Layer 1** 0.04mm Signal Solder Resist Solder Mask GBS Surface Material Bottom Solder 0.02mm **Bottom Overlay** GBO Legend Total thickness: 1.59mm Inner Layer 2(GND) (Scale 1:1) Inner Layer 3 (Scale 1:1) Inner Layer 4 (Scale 1:1) Inner Layer 5 (Scale 1:1)